

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Average Rectified Output Current	lo	0.2	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	4.5	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{ heta JA}$	215	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

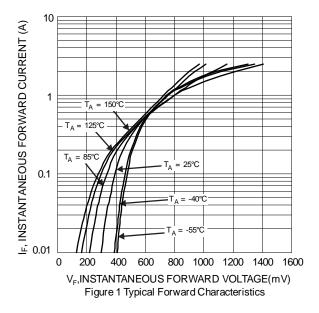
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	V _F	_	0.24	0.29	V	I _F = 1mA, T _J = +25°C
		_	0.30	0.34		$I_F = 10 \text{mA}, T_J = +25 ^{\circ}\text{C}$
		_	0.40	0.46		I _F = 100mA, T _J = +25°C
		_	0.45	0.50		I _F = 200mA, T _J = +25°C
		_	0.39	_		I _F = 200mA, T _J = +125°C
Leakage Current (Note 6)	I _R	_	0.4	2.0	μA	V _R = 10V, T _J = +25°C
		_	1.5	9	μA	$V_R = 30V, T_J = +25^{\circ}C$
		_	0.7	_	mA	$V_R = 30V, T_J = +125$ °C
Junction Capacitance	C _T	_	7		pF	$V_R = 10V, T_J = +25^{\circ}C, f = 1MHz$

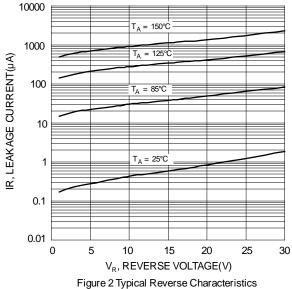
Notes:

^{5.} Device mounted on FR-4 substrate PC board, with minimum recommended pad layout per http://www.diodes.com/package-outlines.html. 6. Short duration pulse test used to minimize self-heating effect.

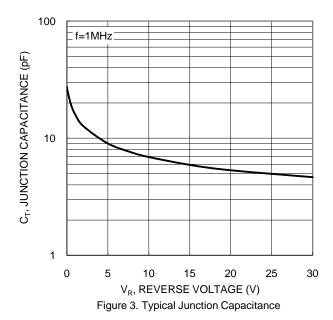


Typical Electrical Characteristics





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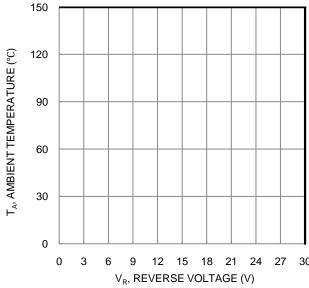


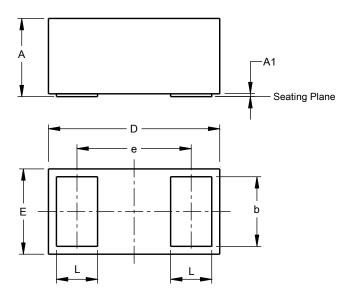
Figure 4. Operating Temperature Derating



Package Outline Dimensions (Note 7)

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-WLB0603-2



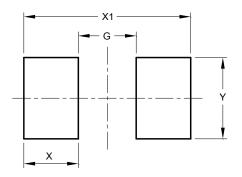
X3-WLB0603-2				
Dim	Min	Max	Тур	
Α	0.250	0.300	0.275	
A1	0.00	0.01	_	
b	0.220	0.280	0.245	
D	0.575	0.625	0.600	
Е	0.275	0.325	0.300	
е	_	_	0.400	
L	0.120	0.180	0.144	
All Dimensions in mm				

Note 7: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-WLB0603-2



Dimensions	Value (in mm)
G	0.206
Х	0.194
Y	0.291
X1	0.594



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